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PATENT TRADEMARK OFFICE

Patent  
Case No.: 53434US009

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: HOGERTON, PETER B.

Application No.: 09/690,600

Group Art Unit: 2827

Filed: October 17, 2000

Examiner: Luan C. Thai

Title: SOLVENT ASSISTED BURNISHING OF PRE-UNDERFILLED SOLDER-BUMPED WAFERS FOR FLIPCHIP BONDING

REQUEST FOR EXTENSION OF TIME UNDER 37 CFR § 1.136(A)Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

CERTIFICATE OF TRANSMISSION	
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Dear Sir:

This is a request for an extension of time under the provisions of 37 CFR § 1.136(a).

Please charge the following fee to Deposit Account No. 13-3723:

- ☐ 37 CFR § 1.17(a)(1) - Extension within first month
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Respectfully submitted,

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By:

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